Low-profile type with 0.9mm in height





Typical Specifications

Ite	ms	Specifications		
Rating (max.)/(mi (Resistive load)	n.)	1mA 5V DC / 50 μA 3V DC 200mΩ max. / 300mΩ max.		
Contact resistance (Initial performance	-	200mΩ max. / 300mΩ max.		
Operating force		Refer to the dimensions.		
Operating life	Without load	10,000 cycles		
Operating life	With load	10,000 cycles (1mA 5V DC)		

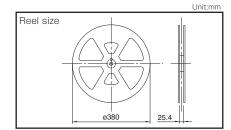
Product Line

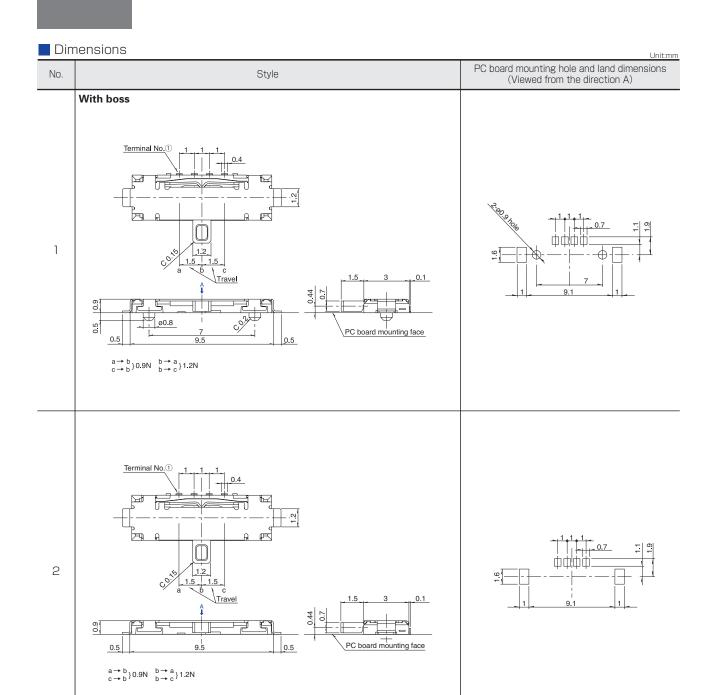
	Operating section	Poles	Positions	e I l'hangeover timing I Soldering I		Location Minimum order unit (pcs.)		Products No.	Drawing	
(mm)	directions					lug	Japan	Export		No.
1.5	Horizontal	1	2	3 Not specified Reflow With 4	4.000	16,000	SSAH110100	1		
1.0	Horizontal	'	3		nellow	Without	4,000	16,000	SSAH120100	2

Packing Specifications

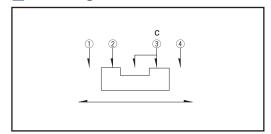
Taping

Nun	nber of packages (p	Tape width	Export package measurements		
1 reel	1 case /Japan	1 case /export packing	(mm)	(mm)	
4,000	8,000	16,000	24	428×413×172	





■ Circuit Diagram (Viewed from Direction A)



	Series		SSAJ	SSAH	SSSS8*	SSAL	SSAG	SSSS7	
Photo		San		N. S.					
Actua	tor	Horizontal	•	•	•	•	•	•	
directi	on	Vertical	_	_	•	_	_	_	
		1-2	•	_	•	•	_	•	
		1-3	_	•	•	_	•	•	
		1-4	_	_	_	_	_	_	
Poles-pos	sitions	2-2	_	_	•	_	_	_	
		2-3	_	_	•	_	_	_	
		2-4	_	_	_	_	_	_	
		4-2	_	_	_	_	_	_	
Т	ravel (mm)		1.4	1.5	1.5, 2	2	1.5	2	
Operating	temperatu	ire range	-10°C to +60°C	-30℃ to +60℃	-40℃ to +85℃	-10°C to	o +60℃	-40°C to +85°C	
Aut	omotive u	se	_	_	_			_	
	Life cycle		*3	* 2	*3	*3	*3		
Ra (Re	ating (max.) d)	10mA 5V DC	1mA 5V DC	0.3A 5V DC	10mA 5V DC		0.3A 4V DC	
	ating (min.) esistive loa				50 <i>μ</i> A	A 3V DC			
Durahility		ting life ut load	10,000 cycles	10,000 cycles	10,000 cycles 100mΩ max.	100,000 cycles	30,000 cycles (Lock side) 100,000 cycles	10,000 cycles 100mΩ max.	
Durability		g life with d: as rating	500mΩ max.	300mΩ max.	10,000 cycles 130mΩ max.	10Ω max.	(Recoil side) 500mΩ max.	10,000 cycles 130mΩ max.	
		contact tance	300mΩ max.	200mΩ max.	70mΩ max.	10Ω max.	200mΩ max.	70mΩ max.	
Electrical performance	Insulation	resistance		10	DOMΩ min. 100V C	OC .		100MΩ min. 500V DC	
	Voltag	ge proof	roof 100V AC for 1minute			500V AC for 1minute			
	Termina	l strength			3N for	lminute			
Mechanical performance	Actuator	Operating direction							
	strength	Pulling direction			10)N	N		
	Cold			-40°C 96h					
Environmental performance	Dry heat		85°C	96h	85°C 500h 85°C 96h			85℃ 500h	
	Dam	p heat	40°C, 90 to 95%RH 96h	60°C, 90 to 95%RH 240h	60°C, 90 to 95%RH 500h		to 95%RH 6h	60℃, 90 to 95%RH 500h	
	Page		75	77	79	82 84		87	

Notes

1. * The operating temperature range for automotive applications can be raised upon request. Please contact us for details.

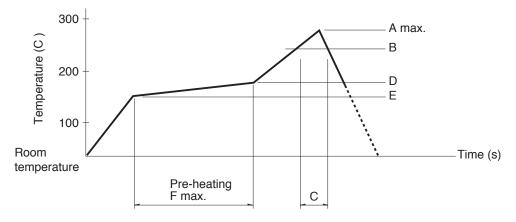
2. Indicates applicability to all products in the series.

Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

Slide Switches Soldering Conditions

3. Temperature profile



Series (Reflow type)		A (℃) 3s max.	B (℃)	C (s)	D (°C)	E (℃)	F(s)	
	Vertical	1-pole, 3-position			40	180	150	120
SSSS2	Horizontal	1-pole, 2-position 1-pole, 3-position 2-pole, 3-position	260	230				
Vertical	Vertical	1-pole, 2-position	050	230				
SSSS7		250						
SSAH, SSAG, SSAJ, SSAL, SSSS8		260						

Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
- Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time	
SSSF, SSSU	350±10℃	3+1/0s	
SSSS2	350±10°C	4s max.	
SSSS9	350±10°C	3s max.	
SSAH, SSAG, SSAJ, SSAL	350±5℃	3s max.	
SSSS8	330±5℃	3s max.	
SSSS7	320±5℃	3s max.	
SSAC	300±10℃	2s max.	

Reference for Dip Soldering (For PC board terminal types)

Series	Ite	ms	Dip soldering		
Jenes	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion	
SSSS2	100°C max.	60s max.	260±5℃	3±1s	
SSSS9	120°C max.	60s max.	260±5℃	5+0/-1s (2 times)	
SSSF, SSSU	100°C max.	60s max.	260±5℃	10±1s/5±1s	
SSAC	100°C max.	60s max.	260±5℃	5±1s	

